

Title (en)

Method for manufacture of a substrate having window-shaped and frame-shaped coating films on the surface thereof

Title (de)

Methode zur Herstellung eines Substrats mit darauf in einer Fenster/Rahmen-Struktur aufgetragenen Filmen

Title (fr)

Méthode pour fabriquer un substrat portant des films en forme de cadre et fenêtre sur sa surface

Publication

EP 0636931 B1 19970604 (EN)

Application

EP 94111050 A 19940715

Priority

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- JP 18379593 A 19930726
- JP 18475493 A 19930727
- JP 18475593 A 19930727

Abstract (en)

[origin: EP0636931A1] A method for manufacturing a substrate having electrically conductive circuits on its surface, window-shaped films on the electrically conductive circuits and a frame-shaped film at the regions not occupied with the window-shaped films, includes the steps of: (a) coating the surface of a transparent substrate with a photoresist composition to cover the electrically conductive circuits-carrying surface of the substrate, followed by forming a photoresist film, (b) superposing a photomask on the surface of the photoresist film formed in step (a) and exposing the thus mask-superposed photoresist film to light, (c) subjecting the substrate obtained in step (b) to development, (d) subjecting the photoresist film left in step (c) to heat-treatment, second exposure to light or no treatment, (e) subjecting the substrate passed the steps (a) to electro-deposition using the electrically conductive circuits on the substrate as one electrode to form electro-deposition coating films, (f) eliminating the photoresist film having been subjected to heat-treatment, second exposure to light or no treatment in step (d) and leaving the electro-deposition coating films formed in step (e), (g) coating the whole surface of the transparent substrate passed the steps (a) to (f) in this order with a negative photoresist composition to cover the electrically conductive circuits-carrying surface of the substrate, followed by forming a functional coating film, (h) exposing the surface opposite to the electrically conductive circuits-carrying surface of the transparent substrate passed the steps (a) to light, and (i) eliminating the uncured parts irrespective of step (h) from the functional coating film. <IMAGE>

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